# Through Shaft Type (360° Rotation)

Through shaft type that enables output covering the whole 360-degree angle due to adoption of 2-phase output





### ■ Typical Specifications

Items	Specifications		
Rated Voltage	5V DC		
Operating life	20,000 cycles		
Total resistance	10kΩ		
Operating temperature range	-40℃ to +120℃		

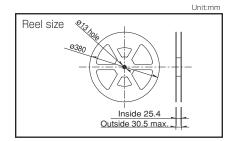
### Product Line

Mounting method	Linearity	Linearity	Through shaft variation	Minimum ord	er unit (pcs.)	Model No.
Woulding method	guarantee range	Linearity		Japan	Export	Widdel No.
Reflow	330° (1-phase) 360° (2-phase)	±3%	φ4.05	1,600	1,600	RDC803101A

### Packing Specifications

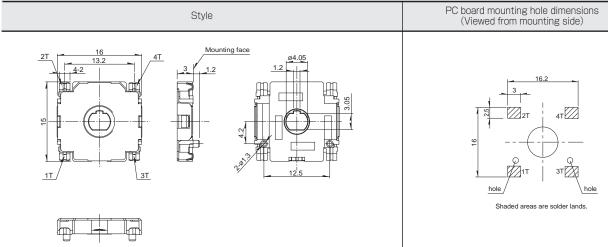
### Taping

Nun	nber of packages (p	ics.)	Tape width	Export package measurements (mm)	
1 reel	1 case /Japan	1 case /export packing	(mm)		
800	1,600	1,600	24	401×401×110	



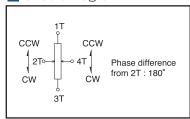
### Dimensions

Unit:mm



**ALPS/ILPINE** 

### Circuit Diagram



# Through Shaft Type Potentiometers List of Varieties

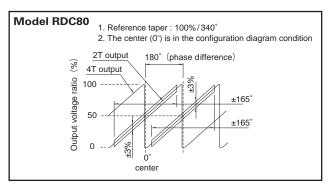
	Туре	Through Shaft Type			
	Series	RDC80			
	Photo				
Dir	ection of lever	Vertical			
Effective	e electrical angle (°)	340 (1-phase), 360 (2-phase)			
Linearity	guarantee range (°)	330 (1-phase), 360 (2-phase)			
Operating	g temperature range	−40℃ to +120℃			
C	perating life	20,000 cycles			
Available	for automotive use	•			
Life cycle (availability)		<b>★</b> 2			
Mechanical Rotational torque		10mN·m max.			
	Total resistance tolerance	±30%			
Electrical performance	Linearity (%)	±3			
	Rated voltage (V DC)	5			
	Cold	-40℃ 168h			
Environmental performance	Dry heat	120°C 168h			
	Damp heat	60°C, 90 to 95%RH 96h			
Т	erminal style	Reflow			
Page		343			

### Note

• Indicates applicability to all products in the series.

# Through Shaft Type / Product Specifications

### ■ Method for Regulating the Linearity



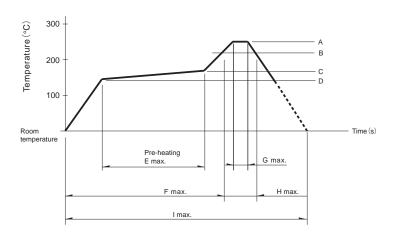
# Through Shaft Type / Soldering Conditions

### Reference for Manual Soldering

Series	Tip temperature	Soldering time		
RDC80	350±5℃	3 <sup>+1</sup> <sub>0</sub> s		

### Example of Reflow Soldering Condition

- 1. Cleaning should not be attempted.
- 2. Type of solder to be used Use cream solder that contains 10 to 15 %wt flux.
- 3. Number of solder applications apply solder only once
- 4. Recommended reflow conditions



Series	А	В	С	D	Е	F	G	Н	I	No. of reflows
RDC80	250℃	_	180℃	150℃	90±30s	_	10±1s	_	_	1 time

### Notes

- When using an infrared reflow oven, solder may not always be applied as intended.
   Be sure to use a hot air reflow oven or a type that uses infrared rays in combination with hot air.
- 2. The temperatures given above are the maximum temperatures at the terminals of the products when employing a hot air reflow method. The temperature of the PC board and the surface temperature of the products may vary greatly depending on the PC board material, its size and thickness. Ensure that the surface temperature of the products does not rise to 250°C or greater.
- 3. Conditions vary to some extent depending on the type of reflow bath used. Be sure to give due consideration to this prior to use.